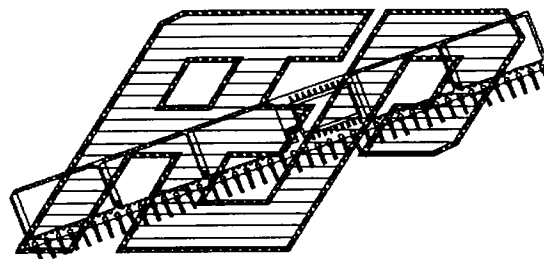


- >> 1,048,576 x 9 Organization
- >> On board BUFFERS for all address and control lines
- >> Low profile design, 0.5 inch stand-off height.
- >> Double sided to maximize bit density
- >> Completely Static operation
- >> TTL compatible
- >> Uses single +5V power supply



**1 MEGAWORD BY 9 BIT HIGH
SPEED STATIC RAM MODULE
WITH ON-BOARD BUFFERS**

DESCRIPTION:

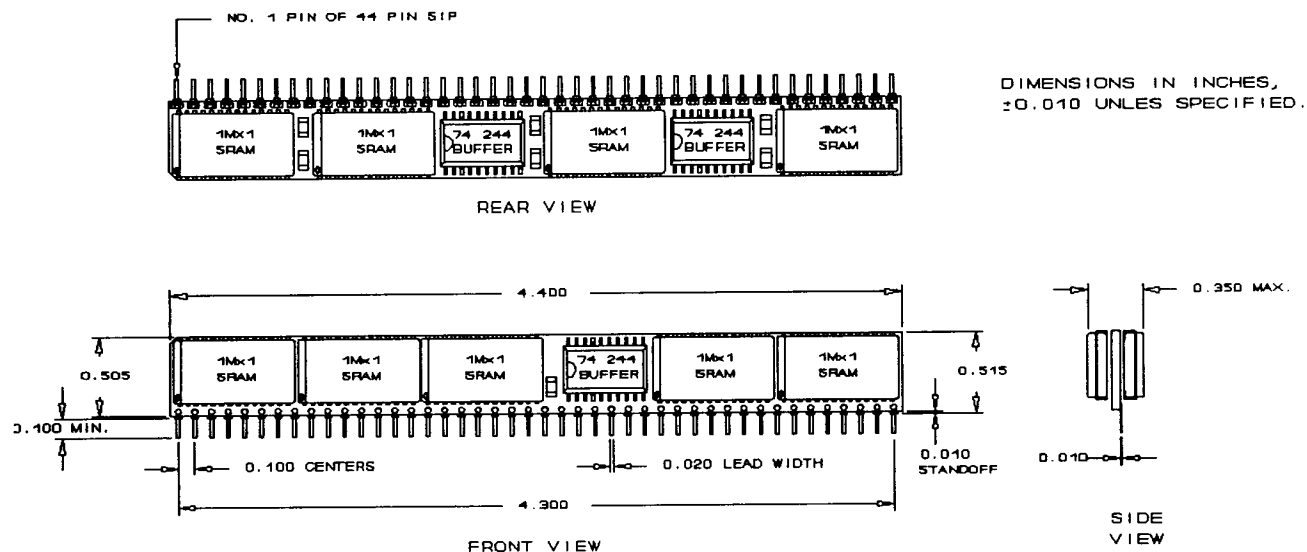
The AEPSS1M9 is a high speed, high density 1 megaword by 9 bit static random access memory module with on board buffering of all address and control lines. Physically it consists of an FR4 PC material substrate surface mounted with nine 1M x 1 high speed static RAM ICs, three 244 type buffer ICs, five 0.18 microfarad decoupling capacitors, and 44 press-in I/O pins in a single-inline-package format.

The module can use any of the 1M x 1 SRAMs with SOJ lead packages and standard pin-out made by any of a variety of manufacturers. A wide range of access speeds are available.

Performance specifications and electrical characteristics are determined by the IC devices used. These items can vary according to the type and manufacturer of the components. The necessary information is obtained from the IC vendors' data sheets, like those attached, or from their data books.

Mechanical dimensions are 0.50 in. high by 4.40 in. long by 0.32 in. wide. The I/O pins are on 0.1 inch center spacing. Also available in 256K x 9 and 64K x 9 versions. These versions can be made in a by 8 bit organization on request.

**SPECIFICATION DRAWING
1M x 9 SRAM**

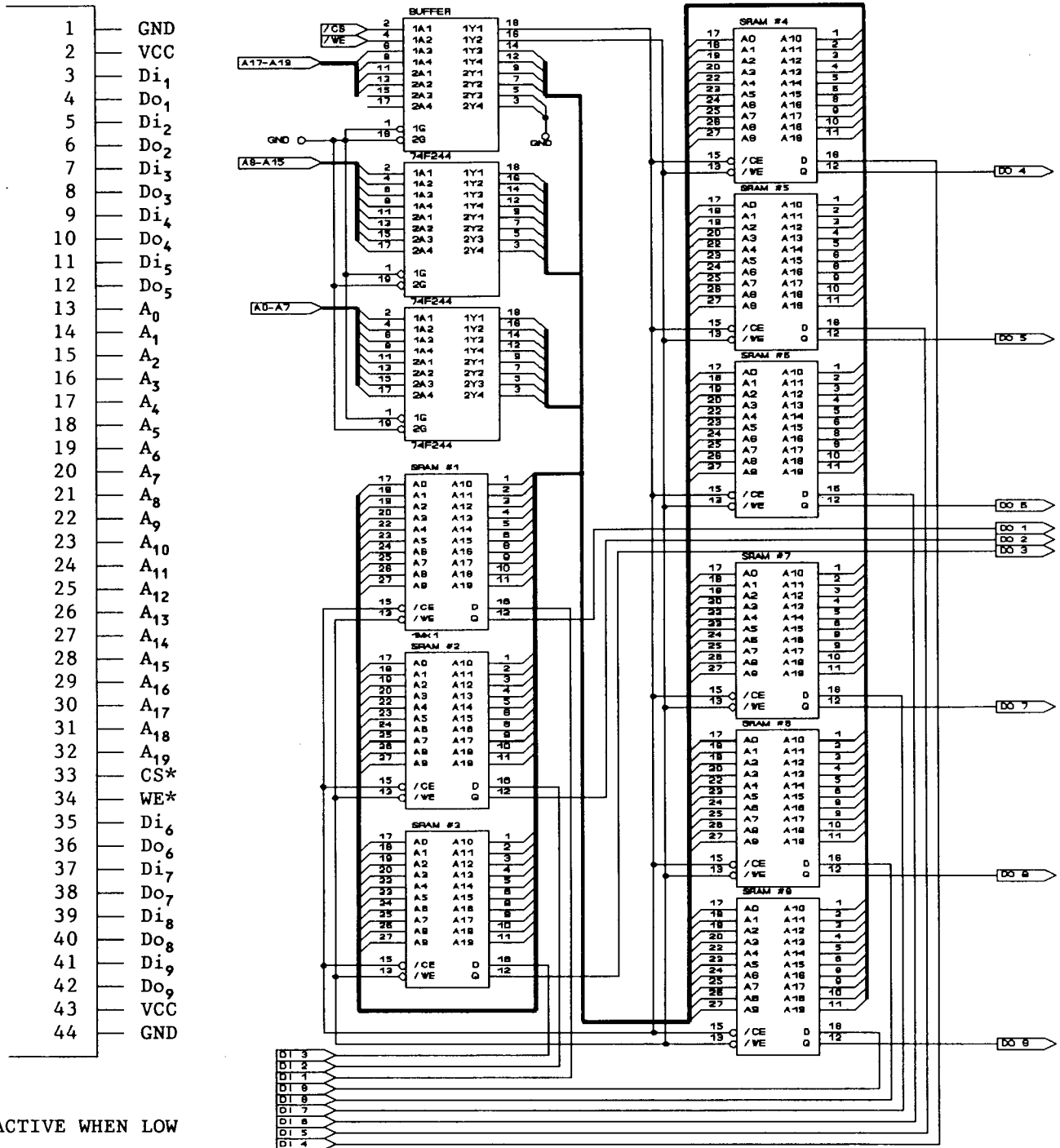


ADVANCED ELECTRONIC PACKAGING

BUFFERED HIGH SPEED 1M x 9 SRAM MODULE

SIP PIN-OUT CONFIGURATION

FUNCTIONAL DIAGRAM



*ACTIVE WHEN LOW

notes:
pins 31 and 32 are no connects on 256K x 9 version.
pins 29, 30, 31, 32 are no connects on and 64K x 9 versions.



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